Isolated Fly-buck Converter

Fly-Buck
BM 5160Q1

\[ V_{IN} = -15.3V \]
\[ PRI = -15.3V \]
\[ V_{SN} = -9V, 200mA \]
\[ GND = 8V - 20V \]

Isolated IGBT Gate Driver

IGBT Gate Driver
ISO5852S

\[ +15V, 200mA \]
\[ -9V \]

Buffer
SN74LVC12SAQ1

PWM_H
PWM_L

Gate_H
Gate_L

Isolated Fly-buck Converter

Fly-Buck
BM 5160Q1

\[ V_{IN} = -15.3V \]
\[ PRI = -15.3V \]
\[ V_{SN} = -9V, 200mA \]
\[ GND = 8V - 20V \]
Thermal Protection of IGBT Modules for HEV/EV Traction Inverters

Project Title: Designed for: Public Release

Assembly Variant: 001

Contact: http://www.ti.com/support

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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